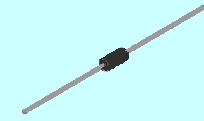


MATERIAL COMPOSITION DECLARATION

Supplier: Fagor Electrónica S. Coop

Package: DO-41



Part Number:

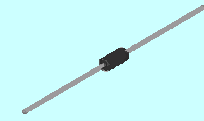
Description: General Purpose, Fast, Ultrafast, Zener and TVS diodes

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS(mg)	MATERIAL MASS(%)	ELEMENT NAME COMPOSITION	CAS Nº	ELEMENT % (BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD WIRE	O2 Free Cu Wire	287.230	88.31%	Cu Oxygen	7440-50-8 7782-44-7	99,9 min 0,0015 max	< 2	< 2	< 2	< 2	< 5	< 5
ENCAPSULATION	Epoxy Moulding Compound	35.110	10.79%	SiO2 (Fused Silica) Polyglycidyl Ether O-Cresol Formaldehyde Novolac Phenolic Resin Sb2O3 Brominated Epoxy resin	60676-86-0 29690-82-2 9003-35-4 1309-64-4 40039-93-8	70-75 10-15 5-10 1-3 1-3	< 2	< 2	< 2	< 2	< 5	< 5
CHIP	Doped Silicon Glass Passivated	0.890	0.27%	Si Ni SiO2 PbO2 Al2O3	7440-21-3 7440-02-0 7631-86-9 1309-60-0 1344-28-1	81,2-82,6 0,8-1,2 8,2-8,6 7,7-8,0 0,7-1,0	< 2	70644 (**)	< 2	< 2	< 5	< 5
SOLDER PASTE	Pb/Sn5Ag2.5 Solder Paste	0.752	0.23%	Pb Sn Ag	7439-92-1 7440-31-5 7440-22-4	91,8 - 92,8 4,5 - 5,5 2,4-2,6	< 2	925013 (*)	< 2	< 2	< 5	< 5
COATING	Sn (100%)	1.084	0.33%	Sn Pb Cu Sb	7440-31-5 7439-92-1 7440-50-8 7440-36-0	99.85 0,05 max 0,05 max 0,05 max	< 2	< 2	< 2	< 2	< 5	< 5

MATERIAL COMPOSITION DECLARATION

Supplier: Fagor Electrónica S. Coop

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Part Number:

Description: General Purpose, Fast, Ultrafast, Zener and TVS diodes

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS(mg)	MATERIAL MASS(%)	ELEMENT NAME COMPOSITION	CAS N°	ELEMENT % (BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
PRINTING INK	Pigments in Acrylate	0.200	0.06%	2- Propenic, polymer with 2-ethyl-2-(Hydroxymethyl)-1,3=propanediol and 3a,4,7,7a-tetrahydro-1,3-isobenzofurandione	53192-18-0	65-70						
				Aluminum Silica	7429-90-5 112945-52-5	15-20 1-5	< 2	< 2	< 2	< 2	< 5	< 5
				Methanone,(1-hydroxycyclohexyl) Phenyl	947-19-3	1-5						
				Benzoic,acid,4-(dimethylamino)-2-ethylhexyl ester	21245-01-2	5-10						
WHOLE ITEM		325.266	100.00%									

Exception according to annex of Directive 2002/95/EC (RoHS):

* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

** Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes

